

Taeyoung Kim

Ph.D
Software Engineer at Intel Corporation
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Areas of interest

VLSI High-Speed I/O: System-level modeling, simulation, and optimization. Platform-level channel simulation design for PCIe 3/4/5, Thunderbolt, USB3, UPI interconnect, jitter decomposition/analysis for high-speed I/O

VLSI Reliability: System-level modeling, simulation, and optimization. System design flow and methods, VLSI Schematic and Layout, Sign off for Reliability

Real-time/Embedded/FPGA System Design and Modeling: HW/SW co-design and co-optimization for real-time/embedded system/FPGA systems design

Experience

Senior Software Engineer, Platform Modeling and Simulation (Signal Integrity & Power Integrity), Product Enablement Solutions Group (PESG), Intel Corporation, Hillsboro, OR, USA Jun, 2017-Present

Software Intern Graduate Level, Signal & Power Integrity, System Modeling Group, Design Technology Solutions (DTS), Intel Corporation, Hillsboro, OR, USA Jun-Sep, 2016

Researcher, Full-time Research Staff, Embedded Systems, Department of Electrical and Computer Engineering, University of Virginia, Charlottesville, VA, USA, Jun.2012–Feb.2013

Lecturer, Full-time Instructor, Programming Language and Computer Security Classes, Kyungmin College, Uijeongbu, Korea, Aug.2007–May.2008

Software Engineering, Assistant Manager, System Software Engineering, Netpia, Inc., Seoul, Korea, Nov.2001–Apr.2004

Software Engineering, Staff, System Software Engineering, eStop, Inc., Seoul, Korea, Aug.1999–Apr.2000

Education

Ph.D. Computer Science, University of California, Riverside, CA, USA
Advisor: Dr. Sheldon X.-D. Tan
Sep.2013–Jun.2017
GPA: 3.87/4.0

M.S. Electrical Engineering, University of Virginia, Charlottesville, VA, USA
Aug.2009–May.2012

M.Eng. Electronics and Computer Engineering, Korea University, Seoul, Korea
Mar.2005–Feb.2007

B.S. Electronic Engineering, Konkuk University, Seoul, Korea
Mar.1997–Feb.2005

Honors and Awards

Dissertation Year Program (DYP) Fellowship Award, University of California, Riverside, 2016-2017
Finalist at ACM student Research Competition (SRC), ICCAD, Nov. 2016
Travel Grant Award at ACM Student Research Competition (SRC), ICCAD, Nov. 2016
Travel Grant Award at ACM Student Research Competition (SRC), ICCAD, Nov. 2015
Travel Grant Award at ACM Student Research Competition (SRC), ICCAD, Nov. 2014
Travel Grant Award at Young Faculty Workshop, Design Automation Conference (DAC), Jun, 2016
Best Poster Research Award at ACM PhD Forum, Design Automation Conference (DAC), Jun, 2015
Travel Grant Award at ACM PhD Forum, Design Automation Conference (DAC), Jun, 2015
Richard Newton Fellowship Award, DAC, Jun. 2014
Dean's Distinguished Fellowship Award, University of California, Riverside, 2013-2015
In Recognition of Exceptional Presentation (2nd place), KSEA Virginia Regional Conference, 2013
Outstanding Academic Performance Award, Korea University, 2007

Professional Activities

2020-Present, IEEE P1924.1 Standard Working Group Member, IEEE
2017-Present, Associate Editor, Integration, the VLSI Journal, ELSEVIER
2017-2018, Program Committee, ACM Student Research Competition at International Conference On Computer Aided Design (ICCAD)
2018-Present, Reviewer, Microelectronics Journal, ELSEVIER
2018-Present, Reviewer, Microelectronics Reliability Journal, ELSEVIER
2018-Present, Reviewer, ACM Journal on Emerging Technologies in Computing Systems (JETC)
2017-Present, Reviewer, ACM Transactions on Embedded Computing Systems (TECS)
2016-Present, Reviewer, ACM Transactions on Design Automation of Electronic Systems (TODAES)
2015-Present, Reviewer, IEEE Transactions On Very Large Scale Integration (VLSI) Systems (TVLSI)

Publications

Books

S. Tan, M. Tahoori, **T. Kim**, S. Wang, Z. Sun, and S. Kiammehr, Long-Term Reliability of Nanometer VLSI Systems: Modeling, Analysis and Optimization, 1st ed. Springer International Publishing, 2019.

Theses

T. Kim, *System-Level Electromigration-Induced Dynamic Reliability Management*, Ph.D. thesis University of California, Riverside, June, 2017

T. Kim, *Detection and Prevention of Forward Head Posture with Body Sensor Networks*, M.S. thesis University of Virginia, Charlottesville, May, 2012

T. Kim, *A Large Scale Indoor Localization System Based on Wireless Sensor Networks*, M.Eng. thesis, Korea University, Seoul, Feb, 2007

Journal Articles

T. Kim, S. X.-D. Tan, C. Cook, and Z. Sun, "Detection of Counterfeited ICs Via On-Chip Sensor and Post-Fabrication Authentication Policy", *Integration, the VLSI Journal*, vol. 63, pp. 31-40, Sep. 2018.

T. Kim, Z. Liu, and S. X.-D. Tan, "Dynamic reliability management based on resource-based EM modeling for multi-core microprocessors," *Microelectronics Journal*, vol. 74, pp. 106-115, Apr. 2018.

S. Wang, **T. Kim**, Z. Sun, S. X.-D. Tan, and M. B. Tahoori, "Recovery-aware Proactive TSV Repair for Electromigration Lifetime Enhancement in 3D ICs" *IEEE Transaction on Very Large Scale Integration Systems (TVLSI)* vol. PP, no. 99, pp. 1-13. doi: 10.1109/TVLSI.2017.2775586

S. Peng, H. Zhou, **T. Kim**, H. Chen, S. X.-D. Tan, "Physics-based Compact TDDDB Models for Low-k BEOL Copper Interconnects with Time-Varying Voltage Stressing," *IEEE Transaction on Very Large Scale Integration (VLSI) Systems (TVLSI)* vol. PP, no. 99, pp. 1-10. doi: 10.1109/TVLSI.2017.2764880

S. X.-D. Tan, H. Amrouch, **T. Kim**, Z. Sun, C. Cook, and J. Henkel, "Recent Advances in EM and BTI induced Reliability Modeling, Analysis and Optimization," *Integration, the VLSI Journal* Volume 60, 2018, Pages 132-152, ISSN 0167-9260.

H. Chen, S. X.-D. Tan, **T. Kim**, and J. Chen, "Analytical Modeling of Electromigration Failure for VLSI Interconnect Tree Considering Temperature and Segment Length Effects," *IEEE Transactions on Device and Materials Reliability (TDMR)*, vol. 17, no. 4, pp. 653-666, Dec. 2017.

X. Huang, V. Sukharev, **T. Kim**, and S. X.-D. Tan, "Dynamic electromigration modeling for transient stress evolution and recovery under time-dependent current and temperature stressing," *Integration, the VLSI Journal*, Volume 58, 2017, Pages 518-527, ISSN 0167-9260

T. Kim, Z. Sun, H. Chen, H. Wang, and S. X.-D. Tan, "Energy and Lifetime Optimizations for Dark Silicon Manycore Microprocessor Considering both Hard and Soft Errors", *IEEE Trans Very Large Scale Integration (VLSI) Systems (TVLSI)*, vol. 25, no. 9, pp. 2561-2574, 2017.

H. B. Chen, S. X.-D. Tan, X. Huang, **T. Kim** and V. Sukharev, "Analytical Modeling and Characterization of Electromigration Effects for Multibranch Interconnect Trees," *IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems (TCAD)*, vol. 35, no. 11, pp. 1811-1824, Nov. 2016.

X. Huang, V. Sukharev, J.-H. Choy, M. Chew, **T. Kim**, S. X.-D. Tan, "Electromigration assessment for power grid networks considering temperature and thermal stress effects," *Integration, the VLSI Journal*, Volume 55, Sep. 2016, Pages 307-315

Z. Yue, **T. Kim**, H. Shin, S. X.-D. Tan, X. Li, H. Chen and H. Wang, "Statistical Rare Event Analysis and Parameter Guidance by Elite Learning Sample Selection", *ACM Transaction on Design Automation of Electronic Systems (TODAES)*, vol. 21, no. 4, p. 56, Sep. 2016.

S. Chen, J. S. Brantley, **T. Kim**, S. A. Ridenour, and J. Lach, "Characterising and minimising sources of error in inertial body sensor networks," *Int. J. Auton. Adapt. Commun. Syst. (IJAAACS)*, vol. 6, no. 3, pp. 253-271, 2013.

W. Y. Lee, K. Hur, **T. Kim**, D. S. Eom, and J. O. Kim, "Large scale indoor localization system based on wireless sensor networks for ubiquitous computing," *Wireless Personal*, vol. 63, no. 1, pp. 241-260, 2012.

D Eom, **T. Kim**, H. Jee, H. Lee and J. Han, "A Multi-Player Arcade Video Game Platform with A Wireless Tangible User Interface", *IEEE Transaction on Consumer Electronics*, 2008.10

Conference Proceedings

Z. Sun, **T. Kim**, M. Chow, S. Peng, H. Zhou, H. Kim, D. Wong and S. X.-D. Tan, "Long-Term Reliability Management For Multitasking GPGPUs" *International Conference on Synthesis, Modeling Analysis and Simulation Methods and Applications to Circuit Design (SMACD2019)*, Lausanne, Switzerland, July 2019.

Y. Ye, **T. Kim**, S. X.-D. Tan, H. Chen and H. Wang, "Comprehensive Detection of Counterfeit ICs Via On-Chip Sensor and Post-Fabrication Authentication Policy," *International Conference on Synthesis, Modeling Analysis and Simulation Methods and Applications to Circuit Design (SMACD2017)*, Taormina, Italy, June 2017.

T. Kim, Z. Sun, C. Cook, J. Gaddipati, H. Wang, H. Chen, S. X.-D. Tan, "Dynamic Reliability Management for Near-Threshold Dark Silicon Processors", *Proc. IEEE/ACM International Conference on Computer-Aided Design (ICCAD2016)*, Austin, TX, Nov. 2016.

Z. Sun, E. Demircan, M. D. Shroff, **T. Kim**, X. Huang and S. X.-D. Tan, "Voltage-Based Electromigration Immortality Check for General Multi-Branch Interconnects", *Proc. IEEE/ACM International Conference on Computer-Aided Design (ICCAD2016)*, Austin, TX, Nov. 2016.

C. Cook, Z. Sun, **T. Kim** and S. X.-D. Tan, "Finite Difference Method for Electromigration Analysis of Multi-Branch Interconnects," *International Conference on Synthesis, Modeling Analysis and Simulation Methods and Applications to Circuit Design (SMACD2016)*, Lisbon, Portugal, Jun. 2016.

T. Kim, Z. Sun, C. Cook, H. Zhao, R. Li, D. Wong, S. X.-D. Tan, "Cross-layer modeling and optimization for electromigration induced reliability", *Proc. IEEE/ACM Design Automation Conference (DAC2016)*, Austin, TX, June, 2016.

X. Huang, V. Sukharev, Z. Qi, **T. Kim**, H. Chen, S. X.-D. Tan, "Physics-Based Full-Chip TDDDB Assessment for BEOL Interconnects", *Proc. IEEE/ACM Design Automation Conference (DAC2016)*, Austin, TX, June, 2016.

T. Kim, X. Huang, H. Chen, V. Sukharev, S. X.-D. Tan, "Learning-based Dynamic Reliability Management for Dark Silicon Processor Considering EM Effects", *Proc. Design, Automation and Test in Europe (DATE2016)*, Dresden, Germany, March 2016 (Acceptance rate = 24%).

X. Huang, V. Sukharev, **T. Kim**, H. Chen, S. X.-D. Tan, "Electromigration Recovery Modeling and Analysis under Time-Dependent Current and Temperature Stressing", *Proc. Asia South Pacific Design Automation Conference (ASP-DAC2016)*, Macao, China, Jan. 2016.

T. Kim, X. Huang, V. Sukharev and S. X.-D. Tan, "Learning-Based Reliability Management for Dark Silicon Systems", *Sixth IEEE International Workshop on Testing Three-Dimensional Stacked Integrated Circuits (3D-TEST2015)*, Anaheim, CA, Oct, 2015.

T. Kim, X. Huang, V. Sukharev, X. X.-D. Tan, "A Dynamic Reliability Management Framework for Dark Silicon", *TECHCON*, Austin, Sep, 2015.

- H. Chen, X. Huang, V. Sukharev, S. X.-D. Tan, **T. Kim**, "Interconnect reliability modeling and analysis for multi-branch interconnect trees," *Proc. IEEE/ACM Design Automation Conference (DAC2015)*, San Francisco, June, 2015.
- T. Kim**, B. Zheng, H. Chen, Q. Zhu, V. Sukharev and S. X.-D. Tan, "Lifetime optimization for real-time embedded systems considering electromigration effects," *Proc. IEEE/ACM International Conference on Computer-Aided Design (ICCAD2014)*, San Jose, CA, Nov. 2014
- T. Wei, **T. Kim**, S. Park, Q. Zhu, S. X.-D. Tan, N. Chang, S. Ula, M. Maasoumy, "Battery management and application for energy-efficient buildings," *Proc. IEEE/ACM Design Automation Conference (DAC2014)*, San Francisco, June, 2014
- T. Kim**, S. Chen, J. Lach, "Detecting and Preventing Forward Head Posture with Wireless Inertial Body Sensor Networks," *International Conference on Body Sensor Networks (BSN2011)*, PP. 125-126, 2011.5
- A.T. Barth, B.C. Bennett, B. Boudaoud, J.S. Brantley, S. Chen, C.L. Cunningham, **T. Kim**, H.C. Powell, Jr., S.A. Ridenour, J. Lach, "Longitudinal High-Fidelity Gait Analysis with Wireless Inertial Body Sensors," *IEEE Wireless Health Conference*, 192-3, 2010
- S. Chen, J. S. Brantley, **T. Kim**, and J. Lach, "Characterizing and Minimizing Synchronization and Calibration Errors in Inertial Body Sensor Networks," in *Proceedings of the Fifth International Conference on Body Area Networks (BodyNet2010)*, Corfu, Greece, 2010, pp. 138-144.
- H. Jee, D. Eom, **T. Kim**, H. Park, H. Lee, J. Han, "Multi-Player VR Game Built Upon Wireless Sensor Network," *The Second International Conference on Ubiquitous Information Management and Communication (ICUIMC)*, PP. 542-544, PP. 542-544, 2008.01
- K. Hwang , **T. Kim**, D. Eom "Proactive Data Delivery Scheme with Optimal Path for Dynamic Sensor Networks", *Lecture Notes in Computer Science (LNCS)*, 412-421, 2007.8
- D. Eom, J. Jang, **T. Kim**, J. Han, "A VR Game Platform Built upon Wireless Sensor Network," *Lecture Notes in Computer Science (LNCS)*, 146-155, 146-155, 2006.11

Teaching

Teaching Assistant, University of California, Riverside
 Winter, 2017 EE260 Advanced VLSI
 Fall, 2016 EE213 Computer-Aided Electronic Circuit Simulation
 Winter, 2016 CS168 Introduction to VLSI
 Fall, 2014 CS100 Software Construction

Teaching Assistant, University of Virginia
 Fall, 2011 ECE3660 Electronics II

Full Time Lecturer, Kyungmin College,
 Spring, 2008, Internet Programming
 Fall, 2007, Internet and Computer Security

Teaching Assistant, Korea University,
 Spring, 2007 KEEE474 Embedded Software
 FALL, 2006 KEEE491 Capstone Project Lab

Graduate Classes

UCR-CS210-Scientific Computing: Grade A+
UCR-CS220-Synthesis of Digital System: Grade A+
UCR-CS229-Machine Learning: Grade A+
UCR-EE260-Embedded Real-time Systems: Grade A+
UCR-EE213-Computer Aided Electrical Circuit Simulation: Grade A
UCR-CS223-Reconfigurable Computing-FPGA Architecture: Grade A
UCR-CS201-Compiler Construction: Grade A
UCR-CS217-GPU Architecture Parallel Programming: Grade A
UCR-CS211-High Performance Computing: Grade A
UCR-CS203A-Computer Architecture
UCR-CS238-Algorithm Technique Computational Biology
UVA-ECE6332-VLSI
UVA-ECE5750-Digital Signal Processing

Professional Membership

2017-Present, Professional Member, Association for Computing Machinery (ACM)
2014-2017, Student Member, Association for Computing Machinery (ACM)
2017-Present, Professional Member, ACM Special Interest Group on Design Automation (SIGDA)
2014-2017, Student Member, ACM Special Interest Group on Design Automation (SIGDA)
2017-Present, Member, Institute of Electrical and Electronics Engineers (IEEE)
2010-2017, Student Member, Institute of Electrical and Electronics Engineers (IEEE)